	REVISIONS		
LTR	DESCRIPTION	DATE (YR-MO-DA)	APPROVED
А	Add device types 02 through 06. Add vendor CAGE 64155. Change CAGE code to 67268.	88-06-28	M. A. FRYE
В	Changes in accordance with N.O.R. 5962-R104-94.	94-02-24	M. A. FRYE
С	Add case outline Y. Make changes to 1.2.2, 1.3, 3.2.1, figure 1, and figure 2. Redrawn ro	99-10-14	R. MONNIN

CURRENT CAGE CODE 67268

THE ORIGINAL SHEET OF THIS DRAWING HAS BEEN REPLACED.

REV																				
SHEET																				
REV																				
SHEET																				
REV STATUS				REV	/		С	С	С	С	С	С	С	С	С	С	С	С		
OF SHEETS				SHE	ET		1	2	3	4	5	6	7	8	9	10	11	12		
PMIC N/A					PAREI ARLES	D BY S E. BE	SORE				D	EFEN	ISE S	UPPL	Y CE	NTEF	R COL	.UMBI	JS	
STAI MICRO DRA		CUIT			CKED Y MON								COL	UMBl	JS, O	HIO 4	43216	•		
THIS DRAWIN FOR U DEPAI	SE BY	ALL	BLE		PROVE CHAEL	D BY A. FRY	Έ						JIT, L SILI		.R, V	OLTA	GE F	REFE	REN	CE,
AND AGEN DEPARTMEN			_	DRA	WING	APPR(87-0	DVAL [)5-29	ATE												
AM:	SC N/A	١		REV	ISION	LEVEL	C				ZE A		GE CC			į	5962-	8759	4	
										SHE	ET		1	OF	12					

DSCC FORM 2233
APR 97
DISTRIBUTION STATEMENT A. Approved for public release; distribution is unlimited.

5962-E469-99

1. SCOPE

- 1.1 <u>Scope</u>. This drawing describes device requirements for MIL-STD-883 compliant, non-JAN class level B microcircuits in accordance with MIL-PRF-38535, appendix A.
 - 1.2 Part or Identifying Number (PIN). The complete PIN is as shown in the following example:

<u>5962-87594</u>	<u>01</u>	<u>X</u>	<u>X</u>
*	*	*	*
*	*	*	*
*	*	*	*
*	*	*	*
Drawing number	Device type	Case outline	Lead finish
	(see 1.2.1)	(see 1.2.2)	(see 1.2.3)

1.2.1 <u>Device type(s)</u>. The device type(s) identify the circuit function as follows:

<u>Device type</u>	Generic number	<u>Circuit function</u>
01	LM185-1.2	Voltage reference diode
02	LM185-2.5	Voltage reference diode
03	LM185BX1.2	Voltage reference diode
04	LM185BX2.5	Voltage reference diode
05	LM185BY1.2	Voltage reference diode
06	LM185BY2.5	Voltage reference diode

1.2.2 <u>Case outline(s)</u>. The case outline(s) are as designated in MIL-STD-1835 and as follows:

Outline letter	Descriptive designator	<u>Terminals</u>	Package style
X	See figure 1	2	TO-46 can
Υ	See figure 1	10	Gullwing flat pack
2	CQCC1-N20	20	Square leadless chip carrier

- 1.2.3 <u>Lead finish</u>. The lead finish is as specified in MIL-PRF-38535, appendix A.
- 1.3 Absolute maximum ratings.

Reverse current (I _R)	30 mA
Forward current (I _F)	10 mA
Maximum power dissipation (PD)	113 mW
Junction temperature (T _J)	+175°C
Lead temperature (soldering 10 seconds):	
Cases X and 2	+300°C
Case Y	+260°C
Storage temperature range	55°C to +150°C
Thermal resistance, junction-to-case (θ _{JC}):	
Case X	80°C/W
Case Y	23°C/W
Case 2	See MIL-STD-1835

STANDARD MICROCIRCUIT DRAWING	SIZE A		5962-87594
DEFENSE SUPPLY CENTER COLUMBUS COLUMBUS, OHIO 43216-5000		REVISION LEVEL C	SHEET 2

1.3 Absolute maximum ratings - Continued.

Thermal resistance, junction-to-ambient (θ_{JA}):

Case X	440°C/W
Case Y	194°C/W
Case 2	100°C/W

1.4 Recommended operating conditions.

Ambient operating temperature range (T_A).....-55°C to +125°C

2. APPLICABLE DOCUMENTS

2.1 <u>Government specification, standards, and handbooks</u>. The following specification, standards, and handbooks form a part of this drawing to the extent specified herein. Unless otherwise specified, the issues of these documents are those listed in the issue of the Department of Defense Index of Specifications and Standards (DoDISS) and supplement thereto, cited in the solicitation.

SPECIFICATION

DEPARTMENT OF DEFENSE

MIL-PRF-38535 - Integrated Circuits, Manufacturing, General Specification for.

STANDARDS

DEPARTMENT OF DEFENSE

MIL-STD-883 - Test Method Standard Microcircuits.

MIL-STD-973 - Configuration Management.

MIL-STD-1835 - Interface Standard For Microcircuit Case Outlines.

HANDBOOKS

DEPARTMENT OF DEFENSE

MIL-HDBK-103 - List of Standard Microcircuit Drawings (SMD's).

MIL-HDBK-780 - Standard Microcircuit Drawings.

(Unless otherwise indicated, copies of the specification, standards, and handbooks are available from the Standardization Document Order Desk, 700 Robbins Avenue, Building 4D, Philadelphia, PA 19111-5094.)

2.2 <u>Order of precedence</u>. In the event of a conflict between the text of this drawing and the references cited herein, the text of this drawing takes precedence. Nothing in this document, however, supersedes applicable laws and regulations unless a specific exemption has been obtained.

STANDARD MICROCIRCUIT DRAWING	SIZE A		5962-87594
DEFENSE SUPPLY CENTER COLUMBUS COLUMBUS, OHIO 43216-5000		REVISION LEVEL C	SHEET 3

3. REQUIREMENTS

- 3.1 <u>Item requirements</u>. The individual item requirements shall be in accordance with MIL-PRF-38535, appendix A for non-JAN class level B devices and as specified herein. Product built to this drawing that is produced by a Qualified Manufacturer Listing (QML) certified and qualified manufacturer or a manufacturer who has been granted transitional certification to MIL-PRF-38535 may be processed as QML product in accordance with the manufacturers approved program plan and qualifying activity approval in accordance with MIL-PRF-38535. This QML flow as documented in the Quality Management (QM) plan may make modifications to the requirements herein. These modifications shall not affect form, fit, or function of the device. These modifications shall not affect the PIN as described herein. A "Q" or "QML" certification mark in accordance with MIL-PRF-38535 is required to identify when the QML flow option is used.
- 3.2 <u>Design, construction, and physical dimensions</u>. The design, construction, and physical dimensions shall be as specified in MIL-PRF-38535, appendix A and herein.
 - 3.2.1 Case outline(s). The case outline(s) shall be in accordance with 1.2.2 herein and figure 1.
 - 3.2.2 Terminal connections. The terminal connections shall be as specified on figure 2.
- 3.3 <u>Electrical performance characteristics</u>. Unless otherwise specified herein, the electrical performance characteristics are as specified in table I and shall apply over the full ambient operating temperature range.
- 3.4 <u>Electrical test requirements</u>. The electrical test requirements shall be the subgroups specified in table II. The electrical tests for each subgroup are described in table I.
- 3.5 <u>Marking</u>. Marking shall be in accordance with MIL-PRF-38535, appendix A. The part shall be marked with the PIN listed in 1.2 herein. In addition, the manufacturer's PIN may also be marked as listed in MIL-HDBK-103 (see 6.6 herein). For packages where marking of the entire SMD PIN number is not feasible due to space limitations, the manufacturer has the option of not marking the "5962-" on the device.
- 3.6 <u>Certificate of compliance</u>. A certificate of compliance shall be required from a manufacturer in order to be listed as an approved source of supply in MIL-HDBK-103 (see 6.6 herein). The certificate of compliance submitted to DSCC-VA prior to listing as an approved source of supply shall affirm that the manufacturer's product meets the requirements of MIL-PRF-38535, appendix A and the requirements herein.
- 3.7 <u>Certificate of conformance</u>. A certificate of conformance as required in MIL-PRF-38535, appendix A shall be provided with each lot of microcircuits delivered to this drawing.
- 3.8 <u>Notification of change</u>. Notification of change to DSCC-VA shall be required in accordance with MIL-PRF-38535, appendix A.
- 3.9 <u>Verification and review</u>. DSCC, DSCC's agent, and the acquiring activity retain the option to review the manufacturer's facility and applicable required documentation. Offshore documentation shall be made available onshore at the option of the reviewer.

STANDARD MICROCIRCUIT DRAWING DEFENSE SUPPLY CENTER COLUMBUS COLUMBUS, OHIO 43216-5000	SIZE A		5962-87594
		REVISION LEVEL C	SHEET 4

TABLE I.	Electrical performance characteristics.

Test	Symbol	Conditions -55°C \leq T _A \leq +125°C unless otherwise specified	Group A subgroups	Device type	Lir	Unit	
		·			Min	Max	1
Reverse breakdown voltage	V _{REF}	I _R = 10 μA	1	01,03, 05	1.223	1.247	V
		10 μA ≤ I _R ≤ 20 μA	2,3]	1.205	1.26	
		I _R = 20 μA	1	02,04, 06	2.462	2.538	V
		20 μA ≤ I _R ≤ 30 μA	2,3	1	2.425	2.575	1
		I _R = 1 mA	1	01,03, 05	1.223	1.247	V
			2,3]	1.205	1.26	
			1	02,04, 06	2.462	2.538	V
			2,3		2.425	2.575	1
		I _R = 20 mA	1	01,03, 05	1.223	1.247	V
			2,3]	1.205	1.26	
			1	02,04, 06	2.462	2.538	٧
			2,3]	2.425	2.575	1
Reverse breakdown voltage change with	ΔV _{REF} /	10 μA ≤ I _R ≤ 1 mA	1	01,03, 05	-1	1	mV
current	ΔI_{R}	20 μA ≤ I _R ≤ 1 mA	2,3		-1.5	1.5	
		20 μA ≤ I _R ≤ 1 mA	1	02,04, 06	-1	1	mV
		30 μA ≤ l _R ≤ 1 mA	2,3]	-1.5	1.5	1
		1 mA ≤ l _R ≤ 20 mA	1	All	-10	10	mV
			2,3	1	-20	20	1
Forward bias voltage	V _F	I _F = 2 mA, T _A = +25°C	1	All	-1	-0.4	V

See footnotes at end of table.

STANDARD MICROCIRCUIT DRAWING	SIZE A		5962-87594
DEFENSE SUPPLY CENTER COLUMBUS COLUMBUS, OHIO 43216-5000		REVISION LEVEL C	SHEET 5

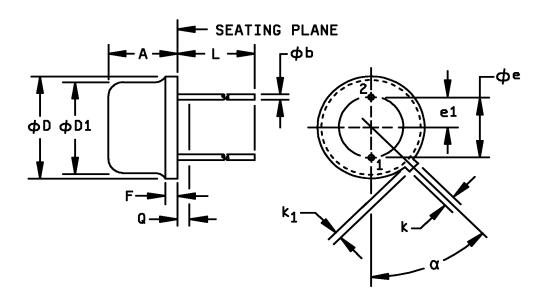
TABLE I. Electrical performance characteristics - Continued.

Test	Symbol	Conditions $-55^{\circ}C \le T_{A} \le +125^{\circ}C$ unless otherwise specified	Group A subgroups	Device type	Limits		Unit
					Min	Max	
Temperature coefficient 1/	T _C		1,2,3	03, 04		30	ppm/°C
				05, 06		50	

- 1/ The average temperature coefficient is defined as the maximum deviation of reference voltage at all measured temperatures between the operating T_{MAX} and T_{MIN} divided by T_{MAX} T_{MIN}. The measured temperatures are -55°C, -40°C, 0°C, +25°C, +70°C, +85°C, and +125°C.
 - 4. QUALITY ASSURANCE PROVISIONS
- 4.1 <u>Sampling and inspection</u>. Sampling and inspection procedures shall be in accordance with MIL-PRF-38535, appendix A.
- 4.2 <u>Screening</u>. Screening shall be in accordance with method 5004 of MIL-STD-883, and shall be conducted on all devices prior to quality conformance inspection. The following additional criteria shall apply:
 - a. Burn-in test, method 1015 of MIL-STD-883.
 - (1) Test condition A, B, C, or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing or acquiring activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1015 of MIL-STD-883.
 - (2) $T_A = +125^{\circ}C$, minimum.
 - b. Interim and final electrical test parameters shall be as specified in table II herein, except interim electrical parameter tests prior to burn-in are optional at the discretion of the manufacturer.
- 4.3 <u>Quality conformance inspection</u>. Quality conformance inspection shall be in accordance with method 5005 of MIL-STD-883 including groups A, B, C, and D inspections. The following additional criteria shall apply.
 - 4.3.1 Group A inspection.
 - a. Tests shall be as specified in table II herein.
 - b. Subgroups 4, 5, 6, 7, 8, 9, 10 and 11 in table I, method 5005 of MIL-STD-883 shall be omitted.

STANDARD MICROCIRCUIT DRAWING	SIZE A		5962-87594
DEFENSE SUPPLY CENTER COLUMBUS COLUMBUS, OHIO 43216-5000		REVISION LEVEL C	SHEET 6

Case X



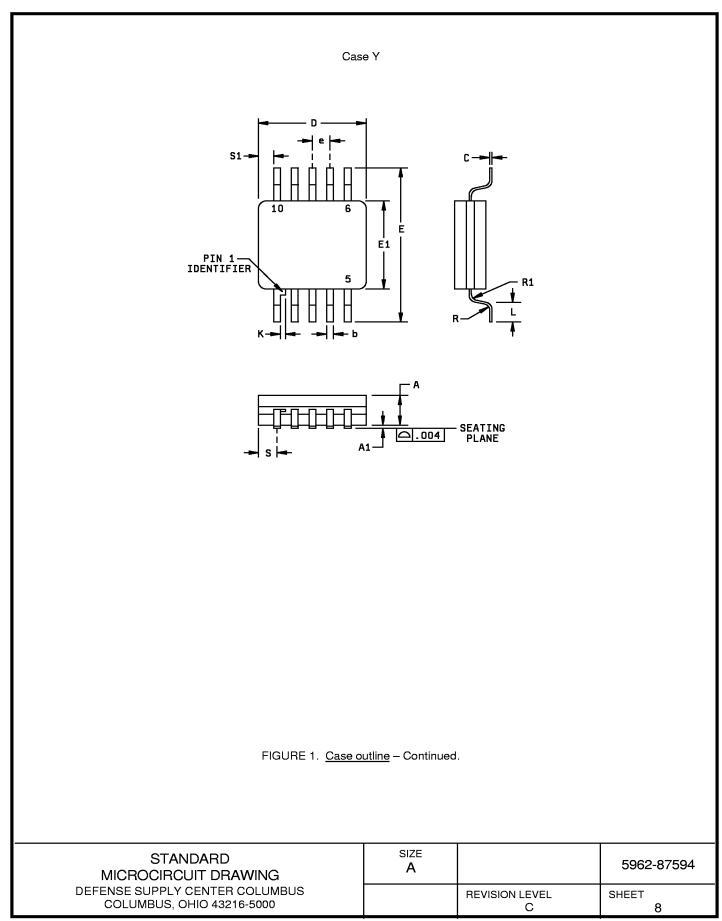
Symbol	Inches		Millim	eters
-	Min	Max	Min	Max
Α	.080	.105	2.03	2.67
φb	.016	.019	0.41	0.48
φD	.209	.219	5.31	5.56
φD1	.178	.195	4.52	4.95
фе		.100		2.54
e1		.050		1.27
F		.030		0.76
k	.036	.046	0.91	1.17
k1	.028	.048	0.71	1.22
L	.500		12.70	
Q		.025		0.64
α	45° BSC		45° E	BSC

NOTES:

- 1. Dimensions are in inches.
- 2. Metric equivalents are given for general information only.
- 3. The U.S. government preferred system of measurement is the metric SI system. However, since this item was originally designed using inch-pound units of measurement, in the event of conflict between the metric and inch-pound units, the inch-pound units shall take precedence.

FIGURE 1. Case outline.

STANDARD MICROCIRCUIT DRAWING	SIZE A		5962-87594
DEFENSE SUPPLY CENTER COLUMBUS COLUMBUS, OHIO 43216-5000		REVISION LEVEL C	SHEET 7



Case Y - continued.

Letter	Inc	hes	Millir	neters	Notes
	Min	Max	Min	Max	
Α	.050	.080	1.27	2.03	
A1	.004	.012	0.10	0.30	
b	.015	.019	0.38	0.48	2
С	.004	.008	0.10	0.20	2
D		.270		6.86	
Е	.400	.420	10.16	10.67	
E1	.236	.261	5.99	6.63	
е	.048	.052	1.22	1.32	
K	.008	.012	0.20	0.30	
L	.037	.043	0.94	1.09	
R	.013	.017	0.33	0.43	
R1	.013	.017	0.33	0.43	
S		.045		1.14	
S1	.005		0.13		

NOTES

- 1. The U.S. government preferred system of measurement is the metric SI system. However, since this item was originally designed using inch pound units of measurement, in the event of conflict between the metric and inch-pound units, the inch-pound units shall take precedence.
- 2. Maximum limit may be increased by .003 inch after lead finish is applied.

FIGURE 1. Case outline - Continued.

STANDARD MICROCIRCUIT DRAWING	SIZE A		5962-87594
DEFENSE SUPPLY CENTER COLUMBUS COLUMBUS, OHIO 43216-5000		REVISION LEVEL C	SHEET 9

Device type		01			
Case outlines	X	Υ	2		
Terminal number	Terminal symbol				
1	V _{REF}	NC	GND		
2	GND	NC	NC		
3		NC	NC		
4		NC	NC		
5		V-	NC		
6		NC	NC		
7		NC	NC		
8		NC	NC		
9		NC	NC		
10		V+	NC		
11			V _{REF+}		
12			NC		
13			NC		
14			NC		
15			NC		
16			NC		
17			NC		
18			NC		
19			NC		
20			NC		

NC = No connection

FIGURE 2. <u>Terminal connections</u>.

STANDARD MICROCIRCUIT DRAWING	SIZE A		5962-87594
DEFENSE SUPPLY CENTER COLUMBUS COLUMBUS, OHIO 43216-5000		REVISION LEVEL C	SHEET 10

TABLE II. Electrical test requirements.

MIL-STD-883 test requirements	Subgroups (in accordance with MIL-STD-883, method 5005, table I)
Interim electrical parameters (method 5004)	
Final electrical test parameters (method 5004)	1, 2, 3 <u>1</u> /
Group A test requirements (method 5005)	1, 2, 3
Groups C and D end-point electrical parameters (method 5005)	1, 2, 3

^{1/} PDA applies to subgroup 1.

4.3.2 Groups C and D inspections.

- a. End-point electrical parameters shall be as specified in table II herein.
- b. Steady-state life test conditions, method 1005 of MIL-STD-883.
 - (1) Test condition A, B, C, or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing or acquiring activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1005 of MIL-STD-883.
 - (2) $T_A = +125$ °C, minimum.
 - (3) Test duration: 1,000 hours, except as permitted by method 1005 of MIL-STD-883.

5. PACKAGING

- 5.1 Packaging requirements. The requirements for packaging shall be in accordance with MIL-PRF-38535, appendix A.
- 6. NOTES
- 6.1 <u>Intended use</u>. Microcircuits conforming to this drawing are intended for use for Government microcircuit applications (original equipment), design applications, and logistics purposes.
- 6.2 <u>Replaceability</u>. Microcircuits covered by this drawing will replace the same generic device covered by a contractor-prepared specification or drawing.
- 6.3 <u>Configuration control of SMD's</u>. All proposed changes to existing SMD's will be coordinated with the users of record for the individual documents. This coordination will be accomplished in accordance with MIL-STD-973 using DD Form 1692, Engineering Change Proposal.

STANDARD MICROCIRCUIT DRAWING	SIZE A		5962-87594
DEFENSE SUPPLY CENTER COLUMBUS		REVISION LEVEL	SHEET
COLUMBUS, OHIO 43216-5000		C	11

6.4 Record of users. Military and industrial users shall inform requires configuration control and the applicable SMD. DSCC will coordination and distribution of changes to the drawings. Users contact DSCC-VA, telephone (614) 692-0525.	ill maintain a record of drawings coverin	d of users and this list will be ng microelectronics devices	used for (FSC 5962) should
 6.5 <u>Comments</u>. Comments on this drawing should be directe 692-0674. 	d to DSCC-VA, Co	olumbus, Ohio 43216-5000,	or telephone (614)
6.6 <u>Approved sources of supply</u> . Approved sources of supply 103 have agreed to this drawing and a certificate of compliance (VA.			
STANDARD MICROCIRCUIT DRAWING	SIZE A		5962-87594
DEFENSE SUPPLY CENTER COLUMBUS COLUMBUS, OHIO 43216-5000		REVISION LEVEL C	SHEET 12

STANDARD MICROCIRCUIT DRAWING BULLETIN

DATE: 99-10-14

Approved sources of supply for SMD 5962-87594 are listed below for immediate acquisition information only and shall be added to MIL-HDBK-103 and QML-38535 during the next revision. MIL-HDBK-103 and QML-38535 will be revised to include the addition or deletion of sources. The vendors listed below have agreed to this drawing and a certificate of compliance has been submitted to and accepted by DSCC-VA. This bulletin is superseded by the next dated revision of MIL-HDBK-103 and QML-38535.

Vendor CAGE number	Vendor similar PIN <u>2</u> /
27014	LM185H-1.2/883
64155	LM185H-1.2/883
27014	LM185WG-1.2/883
27014	LM185E1.2/883
27014	LM185H-2.5/883
64155	LM185H-2.5/883
<u>3</u> /	LM185E2.5883
<u>3</u> /	LM185BXH1.2/883
<u>3</u> /	LM185BXH2.5/883
27014	LM185BYH1.2/883
27014	LM185BYH2.5/883
	27014 64155 27014 27014 27014 64155 3/ 3/ 3/ 27014

- 1/ The lead finish shown for each PIN representing a hermetic package is the most readily available from the manufacturer listed for that part. If the desired lead finish is not listed contact the vendor to determine its availability.
- 2/ Caution. Do not use this number for item acquisition. Items acquired to this number may not satisfy the performance requirements of this drawing.
- 3/ Not available from an approved source of supply.

STANDARD MICROCIRCUIT DRAWING BULLETIN - Continued

Vendor CAGE <u>number</u>	Vendor name <u>and address</u>
27014	National Semiconductor 2900 Semiconductor Dr. P.O. Box 58090 Santa Clara, CA 95052-8090
64155	Linear Technology Corporation 720 Sycamore Drive Milpitas, CA 95035-7487

The information contained herein is disseminated for convenience only and the Government assumes no liability whatsoever for any inaccuracies in the information bulletin.